

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Wen-Kun Yang	01/25/2008
RECEIVING PARTY DATA	
Name:	Advanced Chip Engineering Technology Inc.
Street Address:	No. 65, Guangfu N. Rd.
Internal Address:	Hukou Township
City:	Hsinchu County
State/Country:	TAIWAN
Postal Code:	303
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11946424
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	HK9225US.5
NAME OF SUBMITTER:	Michael A. Jaffe
Total Attachments: 1 source=HK9225US.5-Assignment#page1.tif	

OP \$40.00 11946424

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PATENT
REEL: 020422 FRAME: 0006

For: U.S. Rights
For: U.S. Application
By: Inventor

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of Ten Dollars (\$10.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR:

Wen-Kun YANG
47, Lane 6, An-Kang St.
Hsin-Chu City
Taiwan R.O.C

Nationality: Taiwan, R.O.C.

hereby sell, assign and transfer to

ASSIGNEE:

Advanced Chip Engineering Technology Inc.
No. 65, Guangfu N. Rd.
Hukou Township
Hsinchu County 303, Taiwan, R.O.C.

Country of Formation: Taiwan, R.O.C.

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to any and all improvements which are disclosed in the invention entitled:

FAN OUT TYPE WAFER LEVEL PACKAGE STRUCTURE AND METHOD OF THE SAME

and which is found in (37 C.F.R. §3.21) U.S. patent application executed on even date herewith or [X] in Application No. 11/946,424, filed on November 28, 2007 and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof.

ASSIGNOR hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenant that ASSIGNEE will, upon their request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or their legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal on the date(s) set forth below.

Date: Jan. 25, 2008


Signature of Wen-Kun YANG

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